

AMENDMENTS TO THE SPECIFICATION

Page 1, before the 1st paragraph, please insert the following:

TECHNICAL FIELD

Page 1, before the 2nd paragraph, please insert the following:

BACKGROUND OF THE INVENTION

Before the paragraph bridging pages 1 and 2, please insert the following:

SUMMARY OF THE INVENTION

Page 2, before the 3rd full paragraph beginning with “Figure 1”, please insert the following:

BRIEF DESCRIPTION OF THE DRAWINGS

Page 3, before the 4th full paragraph beginning with “In one of”, please insert the following:

DETAILED DESCRIPTION OF THE INVENTION

Page 3, please amend the 2nd full paragraph as follows:

Figure 4 is a front elevation view similar to figure 3, in which the conducting track or layer part (12) has been widened by ~~(a₂-a₁)~~ with the purpose that when it is desired to incorporate an electronic component (13) the adhesive (14) does not spill over the conducting part.

Page 3, please amend the 3rd full paragraph as follows:

Figure 5 is a front elevation view similar to figure 3, but at a later moment when the electronic component (13) has been duly interlocked and soldered to the copper track (12) at a thickness (i.e., height h₂) greater than 105 microns ~~and height h₂~~.

Please delete the present Abstract of the Disclosure and replace it with the following new Abstract of the Disclosure.

A circuit having a substrate, a first conducting track on the substrate, and a second conducting track on the substrate. The second conducting track is spaced from the first conducting track so as to form an opening between the first conducting track and the second conducting track. The circuit also has an electrical component bridging the opening, the electrical component having an electrical part, a first conducting part; and a second conducting part. The first conducting part is electrically coupled to the first conducting track and the second conducting part is electrically coupled to the second conducting track. The first conducting track extends beyond the first conducting part to a position under the electrical part. An adhesive on the first conducting track adheres the electrical component to the first conducting track.